



US00D771349S

(12) **United States Design Patent**  
**Yang et al.**

(10) **Patent No.:** **US D771,349 S**  
(45) **Date of Patent:** **\*\* Nov. 15, 2016**

(54) **WAFER PILLOW**

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(\*\*) Term: **15 Years**

(21) Appl. No.: **29/539,295**

(22) Filed: **Sep. 11, 2015**

(30) **Foreign Application Priority Data**

Mar. 13, 2015 (CN) ..... 2015 3 0060398

(51) **LOC (10) Cl.** ..... **01-01**

(52) **U.S. Cl.**  
USPC ..... **D1/128**

(58) **Field of Classification Search**

USPC ..... D1/100-130, 199; 426/94, 104, 138,  
426/143, 144, 274, 283, 303, 391, 512, 514,  
426/518, 549; D6/597, 601; D7/675, 560,  
D7/566, 568; D24/101-104; D28/8.1, 8.2;  
D21/385, 386, 707  
CPC ... A23L 1/0067; A23L 1/005; A23L 1/0052;  
A23L 1/217; A23G 9/48; A23G 3/54;  
A23V 2002/00

See application file for complete search history.

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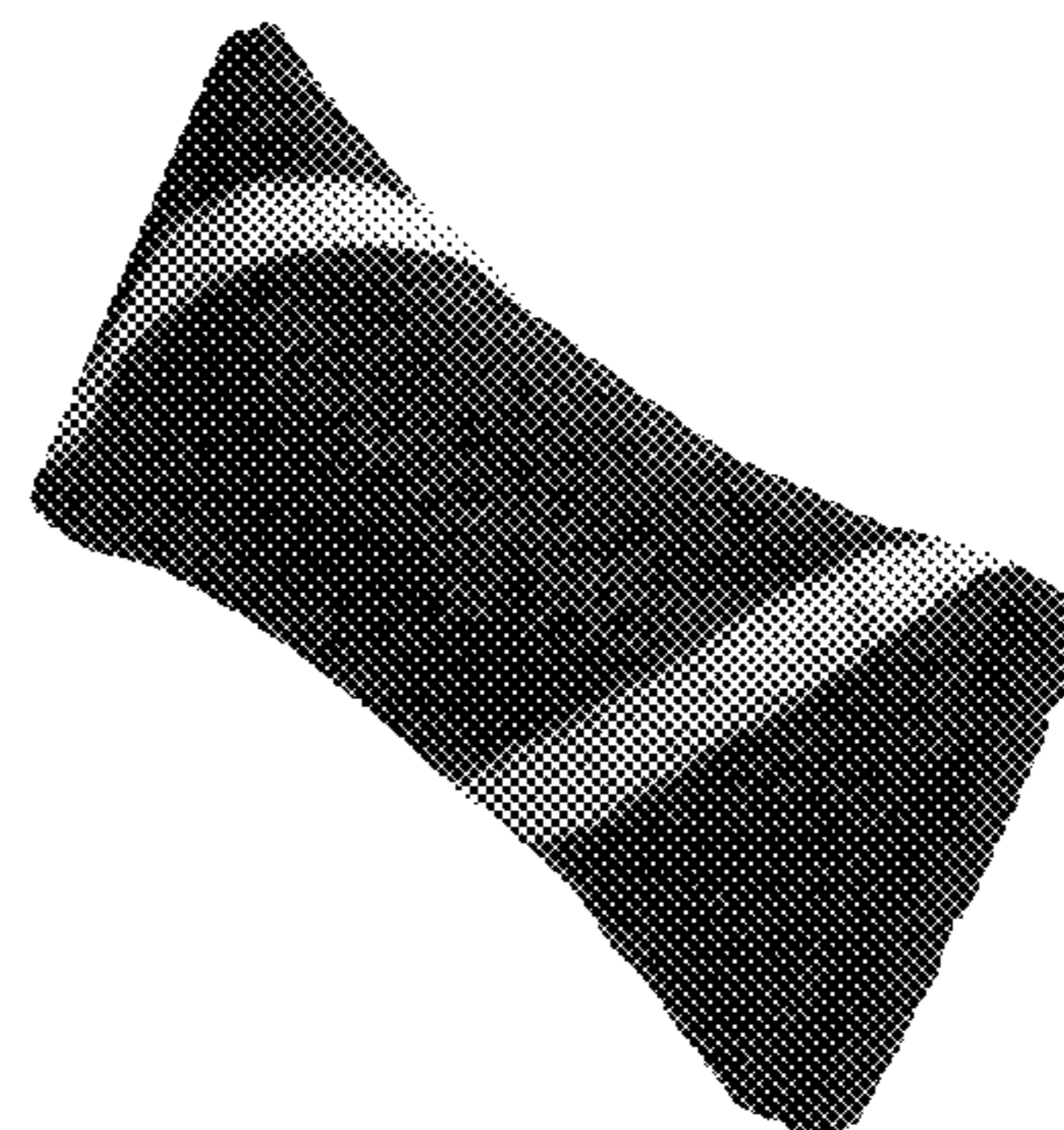
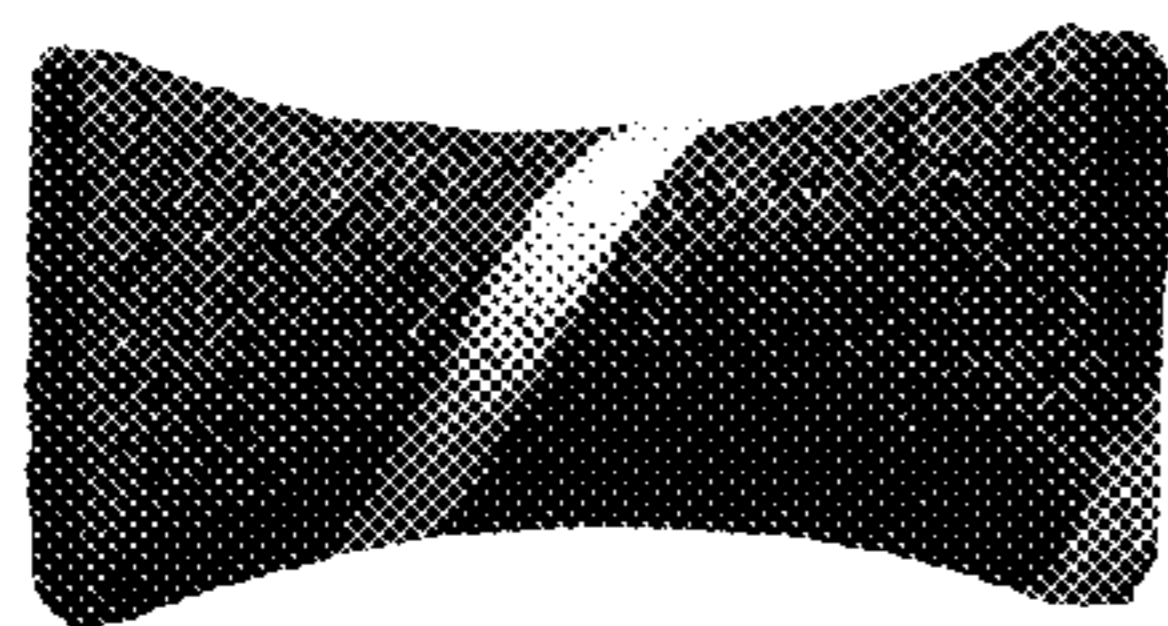
(57) **CLAIM**

The ornamental design for a wafer pillow, as shown and described.

**DESCRIPTION**

FIG. 1 is a front elevation view of a wafer pillow;  
FIG. 2 is a rear elevation view of the wafer pillow of FIG. 1;  
FIG. 3 is a left side elevation view of the wafer pillow of FIG. 1;  
FIG. 4 is a right side elevation view of the wafer pillow of FIG. 1;  
FIG. 5 is a top plan view of the wafer pillow of FIG. 1;  
FIG. 6 is a bottom plan view of the wafer pillow of FIG. 1;  
FIG. 7 is a perspective view of the wafer pillow of FIG. 1;  
FIG. 8 is another perspective view of the wafer pillow of FIG. 1;  
FIG. 9 is another perspective view of the wafer pillow of FIG. 1; and,  
FIG. 10 is another perspective view of the wafer pillow of FIG. 1.

**1 Claim, 2 Drawing Sheets**



# US D771,349 S

Page 2

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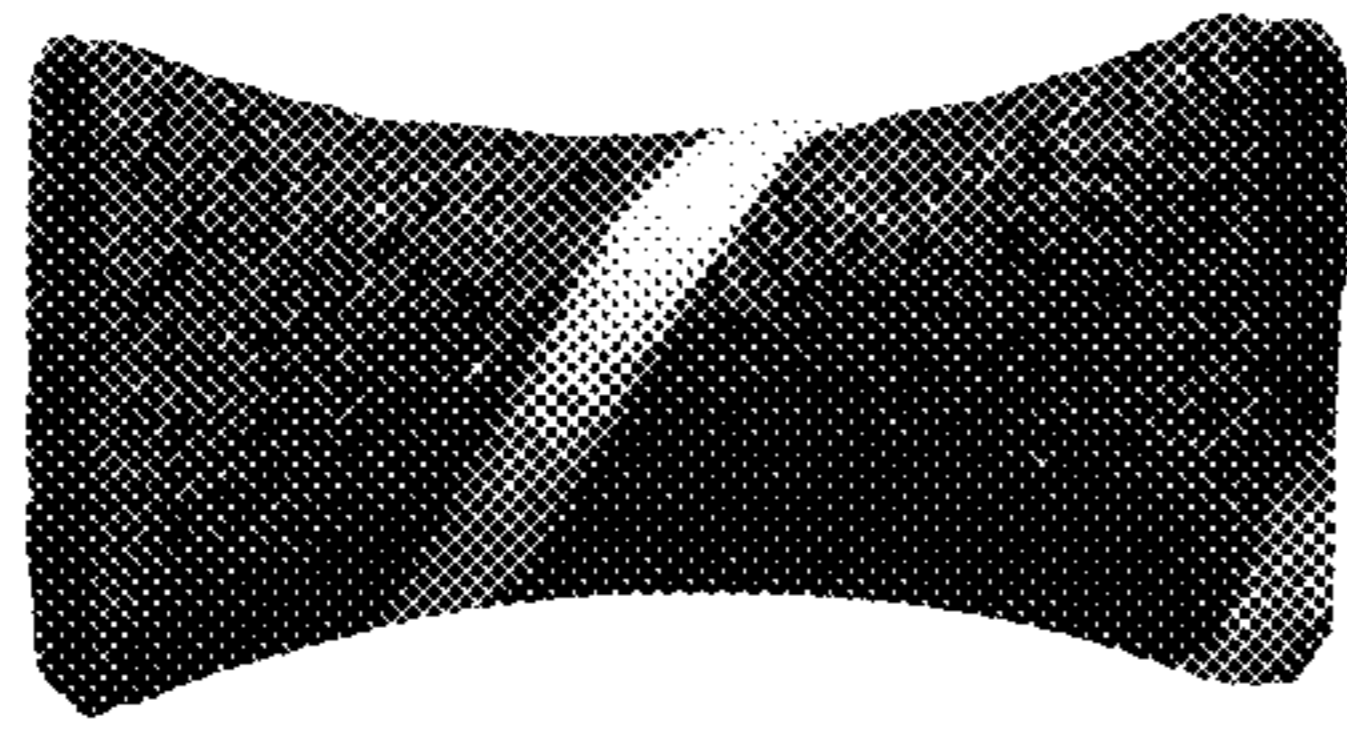


FIG. 1

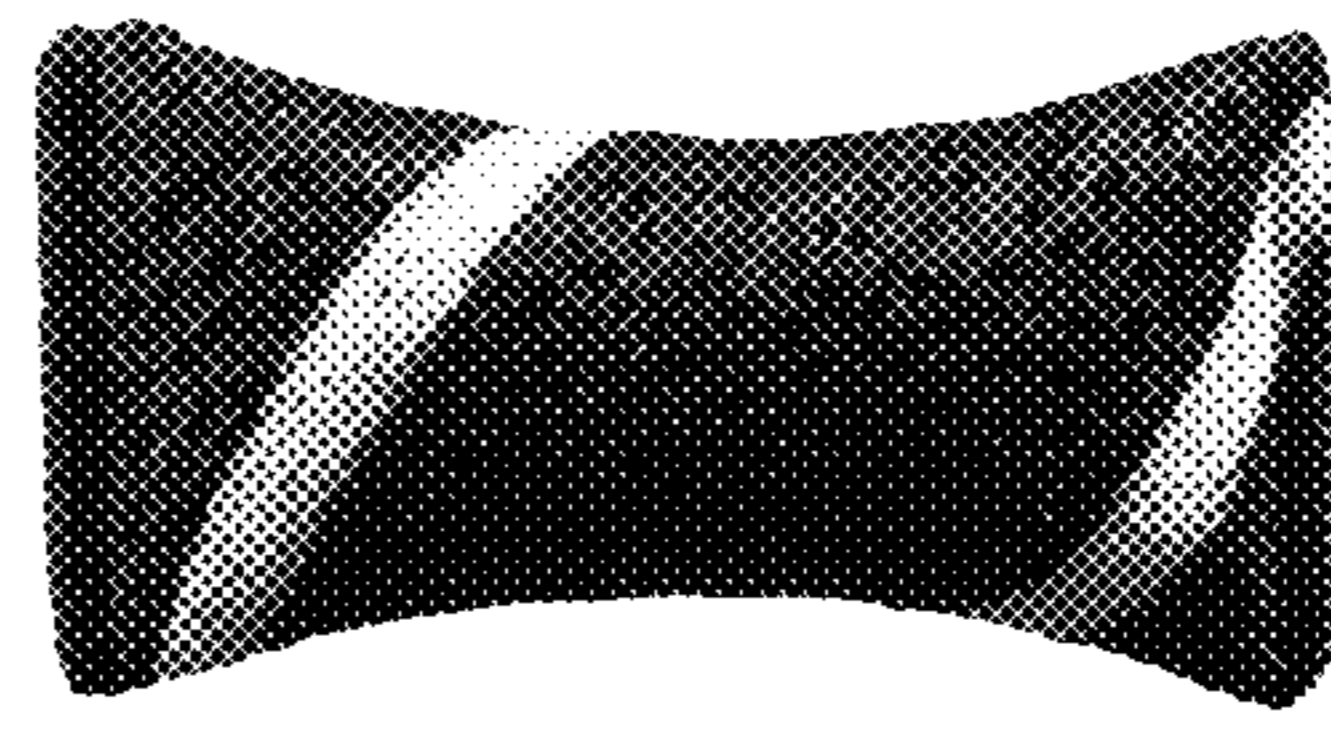


FIG. 2

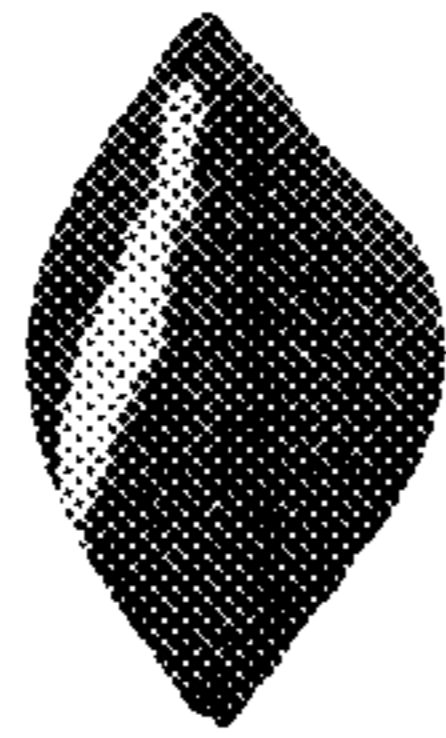


FIG. 3



FIG. 4

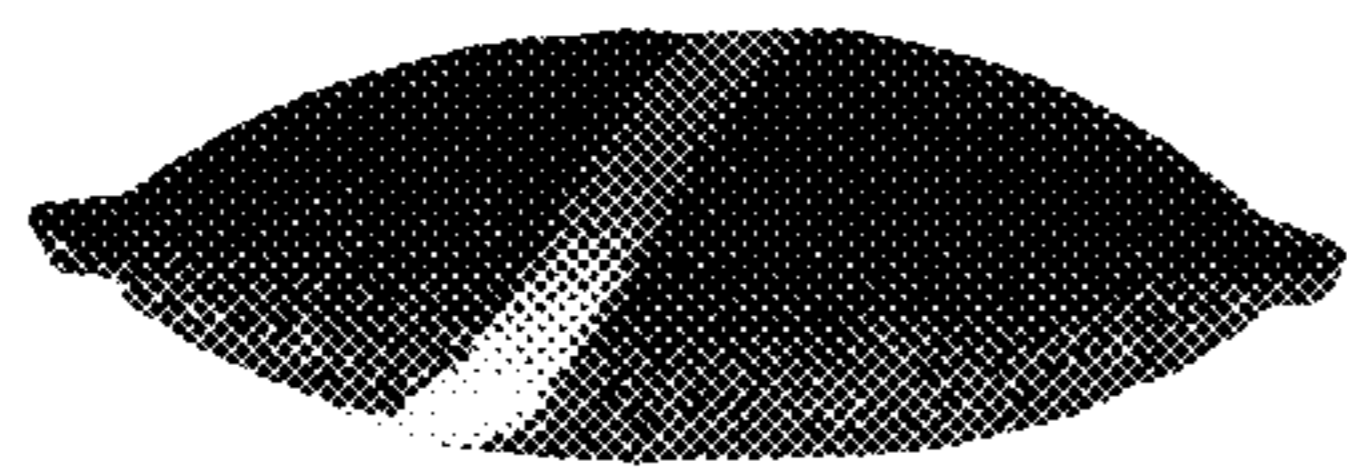


FIG. 5



FIG. 6



FIG. 7

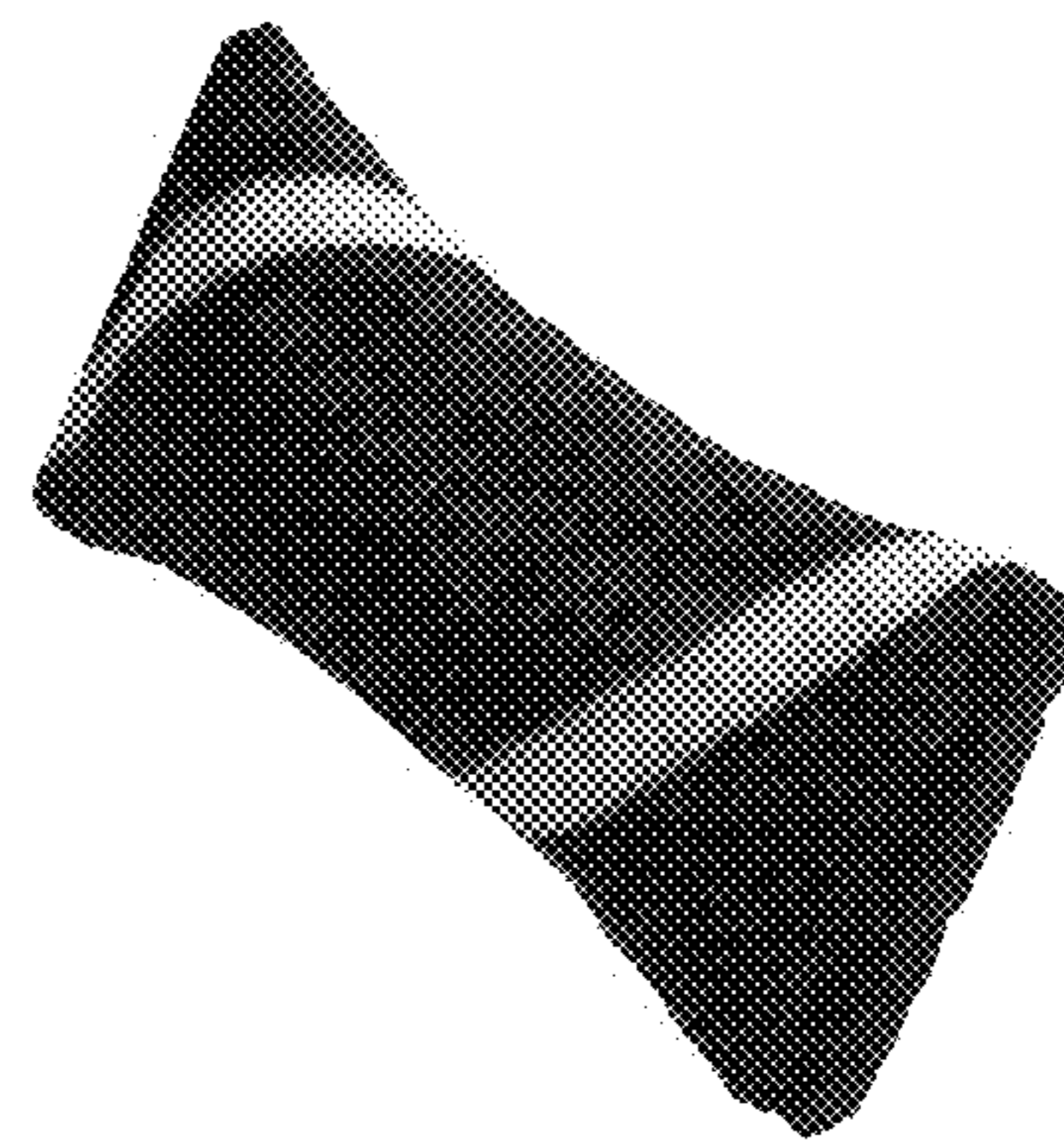


FIG. 8

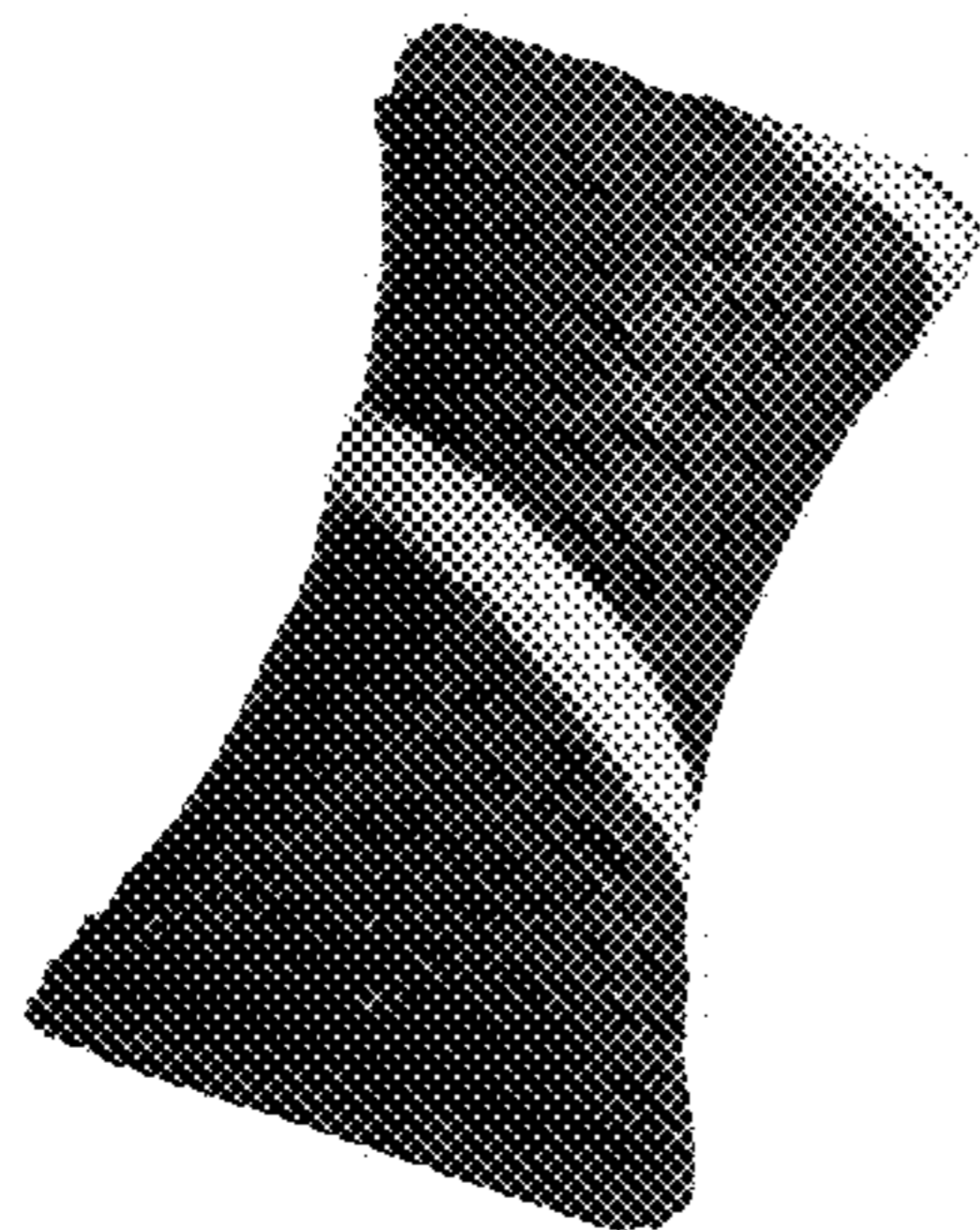


FIG. 9

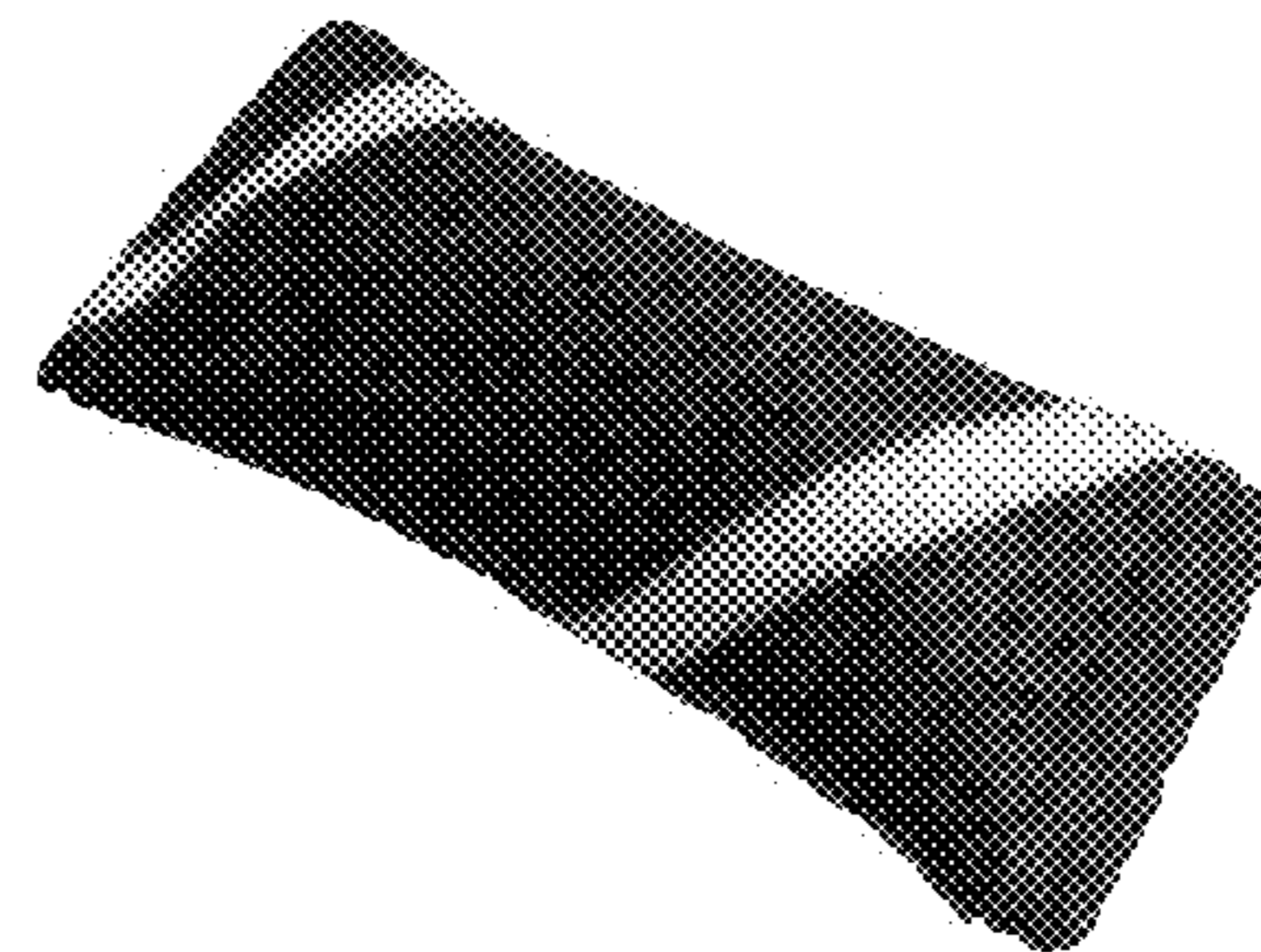


FIG. 10